SCBS195C – FEBRUARY 1991 – REVISED JANUARY 1997

- State-of-the-Art *EPIC-*II*B*<sup>TM</sup> BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Parity Error Flag With Parity Generator/Checker
- Register for Storage of the Parity Error Flag
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

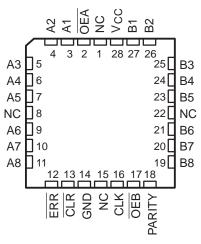
#### description

The 'ABT833 8-bit to 9-bit parity transceivers are designed for communication between data buses. When data is transmitted from the A bus to the B bus, a parity bit is generated. When data is transmitted from the B bus to the A bus with its corresponding parity bit, the open-collector parity-error (ERR) output indicates whether or not an error in the B data has occurred. The output-enable (OEA and OEB) inputs can be used to disable the device so that the buses are effectively isolated. The 'ABT833 provide true data at their outputs.

A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports with the ERR flag. ERR is clocked into the register on the rising edge of the clock (CLK) input. The error flag register is cleared with a low pulse on the clear (CLR) input. When both OEA and OEB are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

SN74ABT833	SN54ABT833 JT PACKAGE SN74ABT833 DW OR NT PACKAGE (TOP VIEW)											
OEA ( A1 ( A2 ( A3 ( A3 ( A5 ( A5 ( A7 ( CLR ( GND (	1 2 3 4 5 6 7 8 9 10 11 12	24 23 22 21 20 19 18 17 16 15 14 13	V <sub>CC</sub> B1 B2 B3 B4 B5 B6 B7 B8 PARITY OEB CLK									

#### SN54ABT833 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



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#### description (continued)

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT833 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74ABT833 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

			INPUTS	6			OUTP	UT AND I/O			
OEB	OEA	CLR	CLK	Ai Σ OF H's	Bi† Σ OF H's	Α	В	PARITY	ERR‡	FUNCTION	
L	Н	х	х	Odd Even	NA	NA	А	L H	NA	A data to B bus and generate parity	
н	L	н	Ť	NA	Odd Even	В	NA	NA	H L	B data to A bus and check parity	
Х	Х	L	Х	Х	Х	Х	NA	NA	Н	Check error-flag register	
н	н	H L H H	No↑ No↑ ↑ ↑	X X Odd Even	х	Z	Z	Z	NC H H L	Isolation§	
L	L	х	х	Odd Even	NA	NA	А	H L	NA	A data to B bus and generate inverted parity	

FUNCTION TABLE

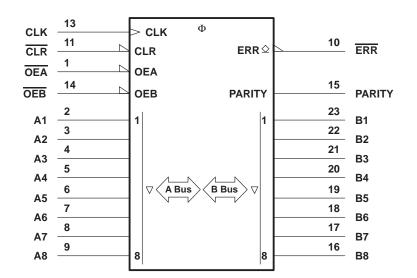
NA = not applicable, NC = no change, X = don't care

<sup>†</sup> Summation of high-level inputs includes PARITY along with Bi inputs.

<sup>‡</sup>Output states shown assume ERR was previously high.

§ In this mode, ERR (when clocked) shows inverted parity of the A bus.

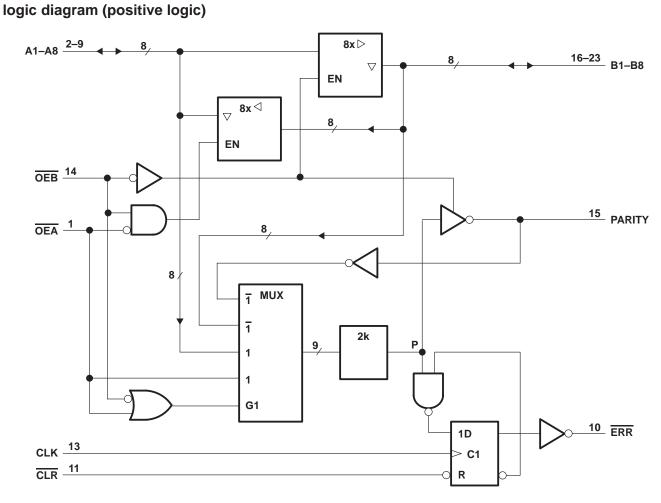
#### logic symbol¶



 $\P$  This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.



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Pin numbers shown are for the DW, JT, and NT packages.

INPUTS		INTERNAL TO DEVICE	OUTPUT PRE-STATE		FUNCTION							
CLR	CLK	POINT P	ERR <sub>n-1</sub> †									
н	$\uparrow$	Н	Н	Н								
н	$\uparrow$	х	L	L	Sample							
н	$\uparrow$	L	Х	L								
L	Х	Х	Х	Н	Clear							

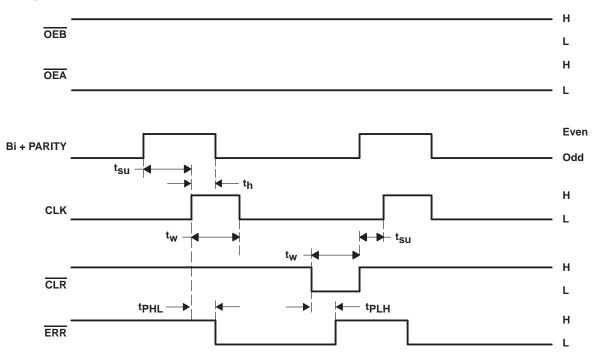
#### ERROR-FLAG FUNCTION TABLE

<sup>†</sup> The state of ERR before any changes at CLR, CLK, or point P



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#### error-flag waveforms



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high or power-off state, $V_{O}$	
Current into any output in the low state, I <sub>O</sub> : SN54ABT833	
SN74ABT833	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0)	
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package	81°C/W
NT package	67°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



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### recommended operating conditions (see Note 3)

			SN54A	BT833	SN74A	BT833	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	N	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	Vcc	0	VCC	V
∨он	High-level output voltage	ERR	7	5.5		5.5	V
ЮН	High-level output current	Except ERR	20	-24		-32	mA
IOL	Low-level output current		202	48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	2	5		5	ns/V
ТА	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	RAMETER	TEST COM		T,	<b>Α = 25</b> °0	C	SN54A	BT833	SN74A	BT833	UNIT	
FA	RAMETER	TESTCO	NDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	lj = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 V,$	I <sub>OH</sub> = -3 mA	2.5			2.5		2.5			
Vari	All outputs	V <sub>CC</sub> = 5 V,	I <sub>OH</sub> = -3 mA	3			3		3		V	
VOH	except ERR	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2				v	
		VCC = 4.3 V	I <sub>OH</sub> = -32 mA	2*					2			
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 24 mA			0.55		0.55			V	
VOL		VCC = 4.3 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	v	
V <sub>hys</sub>					100						mV	
IOH	ERR	V <sub>CC</sub> = 4.5 V,	V <sub>OH</sub> = 5.5 V			20		20		20	μA	
1.	Control inputs	V <sub>CC</sub> = 5.5 V,	VI = V <sub>CC</sub> or GND			±1	¥			±1	μA	
łı	A or B ports					±100		±100		±100		
۱ <sub>IL</sub>	A or B ports	$V_{CC} = 0,$	V <sub>I</sub> = GND			-50		50		-50	μΑ	
IOZH‡		V <sub>CC</sub> = 5.5 V,	$V_{O} = 2.7 V$			50	~	<b>5</b> 0		50	μΑ	
Iozl‡		V <sub>CC</sub> = 5.5 V,	$V_{O} = 0.5 V$			-50	200	-50		-50	μΑ	
l <sub>off</sub>		$V_{CC} = 0,$	$V_{I} \text{ or } V_{O} \leq 4.5 \text{ V}$			±100	0			±100	μΑ	
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50	9	50		50	μA	
ΙΟ§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-200¶	-50	-200¶	-50	-200¶	mA	
		V <sub>CC</sub> = 5.5 V,	Outputs high		1	250		250		250	μΑ	
ICC	A or B ports	I <sub>O</sub> = 0,	Outputs low		24	38¶		38¶		38¶	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μA	
	Dete innute	V <sub>CC</sub> = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	mA	
$\Delta I_{CC}^{\#}$	Data inputs	Other inputs at V <sub>CC</sub> or GND	Outputs disabled			50		50		50	μΑ	
Control inputs		$V_{CC}$ = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND				1.5		1.5		1.5	mA	
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			4.5						pF	
Cio	A or B ports	V <sub>O</sub> = 2.5 V or 0.5 V			10.5						pF	

\* On products compliant to MIL-PRF-38535, this parameter does not apply.

<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V.

<sup>‡</sup> The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ These limits may vary among suppliers.

 $^{\#}$  This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.



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# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V <sub>CC</sub> = T <sub>A</sub> = 2	= 5 V, 25°C	SN54A	BT833	SN74A	BT833	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
t	Pulse duration	CLK high or low	3		3	15	3		20	
tw	Fuse duration	CLR low	3		3	35	3		ns	
		B or PARITY high	9.8		9.8	2	9.8			
t <sub>su</sub>	Setup time before CLK↑	B or PARITY low	8.1		8.1		8.1		ns	
		CLR	2		02		2			
t <sub>h</sub>	Hold time after CLK↑	B or PARITY	0		<b>č</b> 0		0		ns	

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

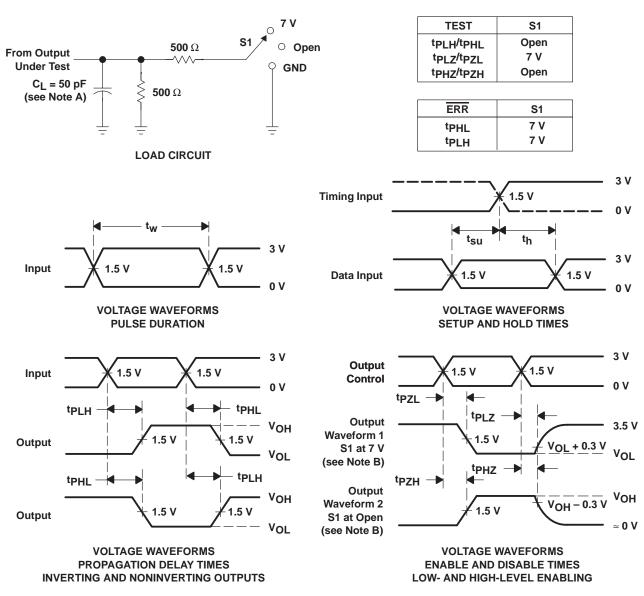
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V T	CC = 5 V A = 25°C	!, ;	SN54A	BT833	SN74A	BT833	UNIT	
	(INFOT)	(001-01)	MIN	TYP†	MAX	MIN	MAX	MIN	MAX		
<sup>t</sup> PLH	A or B	B or A	1.2	2.8	4.8	1.2	5.4	1.2	5.3	-	
<sup>t</sup> PHL	AUB		1	3	4.8‡	1	5.4	1	5.3‡	ns	
<sup>t</sup> PLH	А	PARITY	2.1	5.5	9.5	2.1	11.3	2.1	11.2	ns	
<sup>t</sup> PHL	Α.		2.5	5.3	9.7	2.5	11,1	2.5	11	115	
<sup>t</sup> PZH	OE	PARITY	2.6	6.2	8.5	2.6	10.6	2.6	10.5	10.5 ns	
<sup>t</sup> PZL				2.6‡	5.8	8.6	2.6‡ <	10.1	2.6‡	10	115
<sup>t</sup> PLH	CLR	ERR	1	3.2	4.8‡	(e)	5.3	1	5.2		
<sup>t</sup> PHL	CLK	EKK	1.2‡	2.8	5.7	1.2‡	6.3	1.2‡	6.2	ns	
<sup>t</sup> PZH			1	3.7	5.8‡	S 1	6.6	1	6.5‡		
<sup>t</sup> PZL	OE	A, B, or PARITY	1.3‡	3.8	5.8	1.3‡	6.6	1.3‡	6.5‡	ns	
<sup>t</sup> PHZ	OE	A, B, or PARITY	1.9‡	4.4	7.3	1.9‡	8	1.9‡	7.9		
<sup>t</sup> PLZ	0E	A, D, UI PARITY	2.2‡	4.4	7.7	2.2‡	8.2	2.2‡	8.1	ns	

<sup>†</sup> All typical values are at  $V_{CC} = 5 V$ .

<sup>‡</sup> These limits may vary among suppliers.



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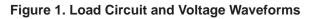


PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns

D. The outputs are measured one at a time with one transition per measurement.







10-Dec-2020

### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ABT833DW	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT833	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(<sup>6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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### TUBE



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74ABT833DW	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



# LAND PATTERN DATA



NOTES:

A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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